Topics and Abstracts:

Speaker	**Mr CHONG Chan Pin**
Company	**Kulicke & Soffa Pte Ltd**
Designation	**Senior VP, EA/APMR & Wedge Bonders Business Units**
Title of Presentation	**SMT Placement Challenges in the Manufacture of Flexible Circuits**
Abstract	Placing traditional surface mount technology (SMT) components onto a flexible substrate provides new challenges that manufacturers may not be familiar with or have needed to consider before now. Miniaturization combined with high accuracy and force control demand ever tighter process controls in order to produce a quality product efficiently in mass production. Transporting the flexible substrate, whether as stand-alone circuits or panels, or on a continuous reel, can present a continuously moving target on which to place components accurately and repeatedly, this can vary significantly compared to more traditional SMT rigid assemblies, and therefore needs to be properly understood. Moisture ingress, warp and twist and the support method all are critical process factors which if understood can be controlled to enable a stable and efficient process. This talk will explore the key considerations to provide an understanding of this growing market and how to maximize the yield and productivity within the SMT placement Process.

Biography

Chan Pin was appointed as Senior Vice President of K&S' EA/APMR & Wedge Bonders Business Units in December 2016. He joined K&S in 2014 as Vice President of Wedge Bonders business unit and has successfully turnaround the business and led the team to higher growth by diversifying the business into the battery bonding market.

Chan Pin is a technology industry veteran with more than 24 years of engineering and operations experience in the semiconductor and electronics industry. He started his career first as a Process and Test Engineer at Motorola Pagers and Cellular group and pioneered multiple factories in Asia before advancing to the role of Manufacturing Manager at Flextronics.

In 1999, Chan Pin joined KLA-Tencor and held a number of diverse positions, including Senior Technical Director of Engineering and General Manager of Strategic Business Unit in Greater China. Chan Pin then pioneered the efforts of starting the MEMS factory in Singapore when he became the Vice President of Sales and General Manager at Form Factor.

Most recently, he was the Global President & CEO at Everett Charles Technologies, managing and leading in test and probe technologies. Chan Pin received his bachelor's degree in Electrical Engineering and Computer Science from the State University of New York at Buffalo and a master's degree in Business Administration from the University of Leicester, United Kingdom. A Singaporean national, he is a military reserve commander.